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NEWS RELEASE

Mitsui Kinzoku Accelerates Enhancement of MicroThin™ Production Capacity

–Monthly Production Capacity to Reach 5.6 million m² in FY2027, Up 0.7 million m² –

Mitsui Kinzoku Company, Limited (President: Seiji Ikenobu; "Mitsui Kinzoku") announces that it will accelerate its plan to bolster its MicroThin™ production capacity by FY2030, which it announced in the Enhanced Production Capacity for MicroThin™ news release dated August 7, 2026. In the previous news release, Mitsui Kinzoku announced that it would achieve production capacity of 6 million m^2 per month in FY2028. Now, the plan is to increase monthly production to 5.2 million m^2 in the second half of FY2026, to 5.6 million m^2 in FY2027, and then to 6.2 million m^2 in FY2028. MicroThin™ is manufactured at its Ageo Plant and Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn. Bhd). The plan has been accelerated by bringing forward the plan to enhance productivity and install some equipment at the Ageo Plant, and it involves without major additional capital investments.

Demand for semiconductor package substrates used in data centers and memory applications is increasing. At the same time, as photonic-electronic convergence advances, demand for optical module applications in multilayer PCBs for communication infrastructure is also growing. In response to this rapid increase in demand, Mitsui Kinzoku has decided to accelerate its plan for increasing its production capacity beyond what was announced in the news release on August 7. This will enable Mitsui Kinzoku to meet higher-than-anticipated demand without a large amount of additional capital investment.

The Company will contribute to the realization of a sustainable society by implementing its vision for 2030, "Building new businesses －and the future－ with our material intelligence," based on its purpose, "We promote the well-being of the world through a spirit of exploration and diverse technologies."

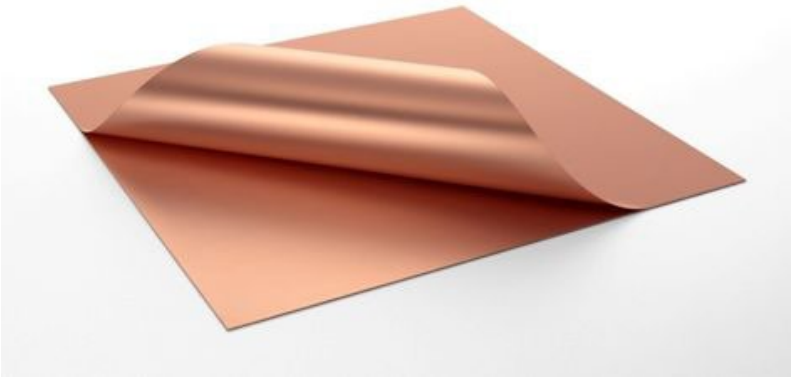
■ MicroThin™ production capacity (Unit: 10,000 m^2 / month) (for reference)

	H1 FY2026	H2 FY2026	FY2027	FY2028	FY2030
Ageo Plant	250	250→280	260→300	280→300	* Under consideration
Malaysia Plant	240	240	260	320	* Under consideration
Total	490	490→520	520→560	600→620	800

* The figures before and after each arrow (→) represent production capacity before and after the productivity improvements and the accelerated installation of certain equipment.

[Contact]
Corporate Communications Department, Mitsui Kinzoku Company, Limited
TEL: +81-3-5437-8028 Email: PR@mitsui-kinzoku.com

Picture of MicroThin™



Top: Copper carrier foil (thickness: 18μm or 12μm)
Bottom: Extremely-thin copper foil (thickness: 1.5μm to 5μm)